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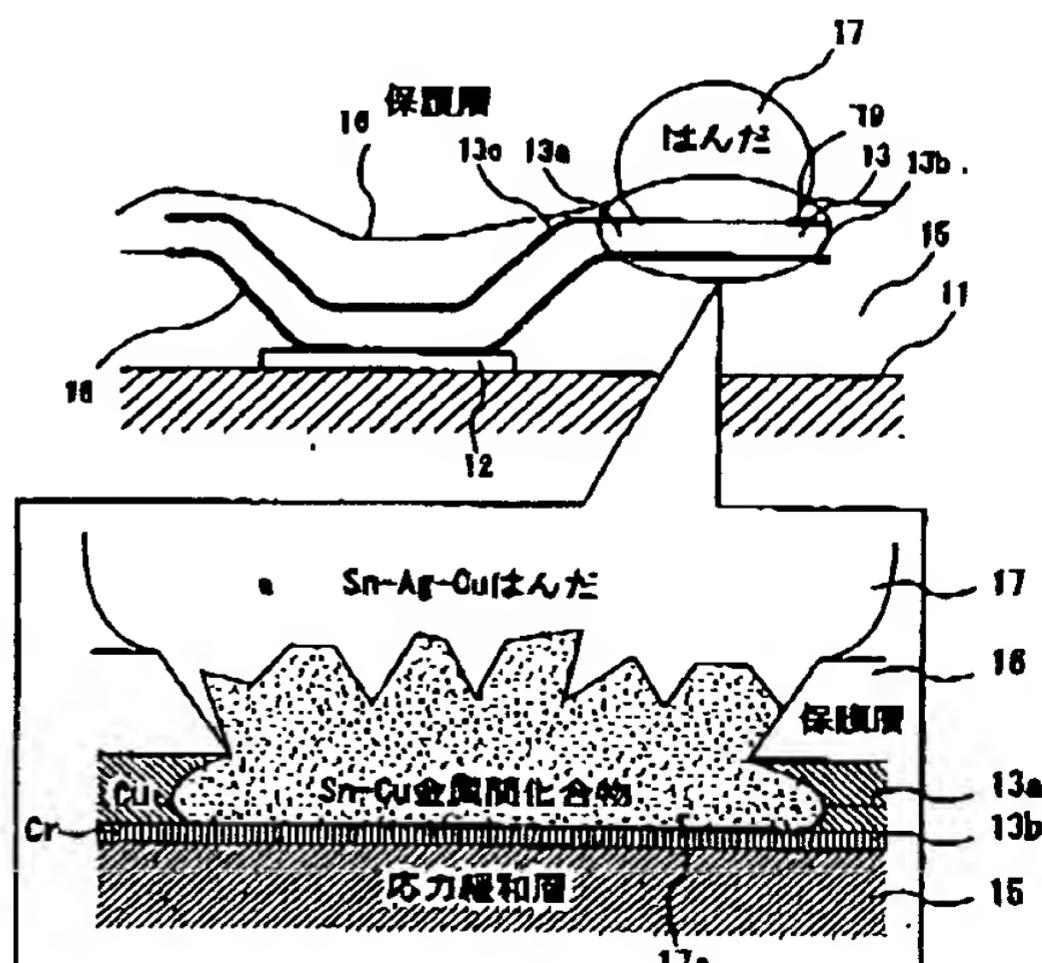
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国際調査報告書

(54) Title: WIRING BOARD AND ITS PRODUCTION METHOD, SEMICONDUCTOR DEVICE AND ITS PRODUCTION METHOD, AND ELECTRONIC APPARATUS

(54) 発明の名称 配線基板およびその製造方法、半導体装置およびその製造方法並びに電子機器

(57) Abstract

A high-density wiring board having a high connection reliability and produced at low cost. The wiring board is characterized by comprising a board having an electrode and covered with an insulating layer in which a hole is made so as to expose the electrode, a wiring connected to the electrode and formed of a layer adhering to the insulating layer and made of Cr or Ti and a layer adhering to the Cr or Ti layer and made of Cu, a protective film covering the wiring and having therein a hole for soldering, and solder for external connection formed in the hole by diffusion-alloying the Cu layer and reaching the Cr or Ti layer for establishing connection.



16... PROTECTIVE LAYER

17... SOLDER

a... Sn-Ag-Cu SOLDER

17a... Sn-Cu INTERMETAL IC COMPOUND

15... STRESS RELAXATION LAYER

(81系1)

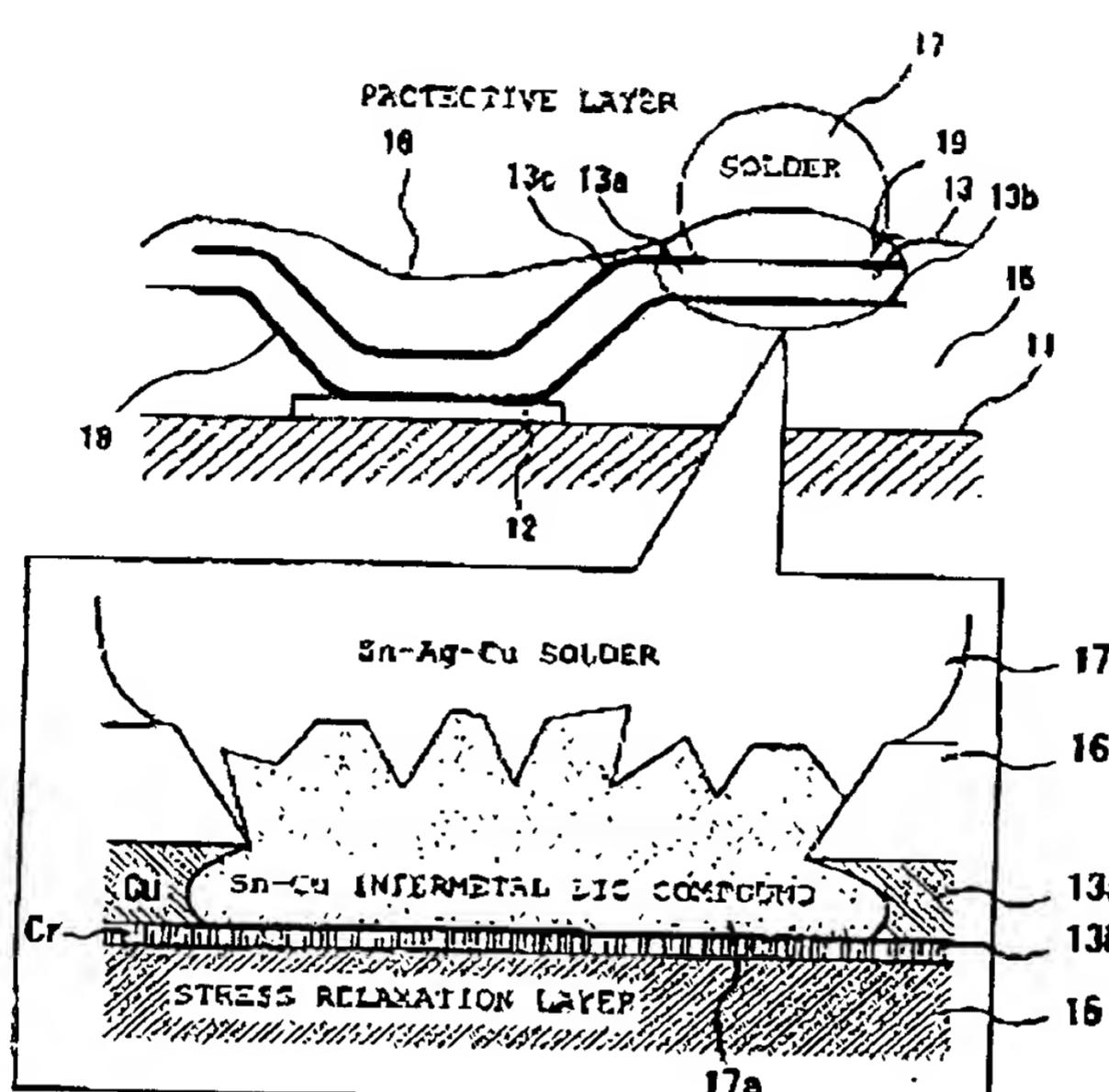
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WO0052755

WIRING BOARD AND ITS PRODUCTION METHOD, SEMICONDUCTOR DEVICE AND ITS PRODUCTION METHOD, AND ELECTRONIC APPARATUS

HITACHI, LTD.

Inventor(s): NARIZUKA, Yasumori ; ITOU, Mitsuko ; YAMAGUCHI, Yoshihide ; TENMEI, Hiroyuki
 Application No. JP0000695 JP, Filed 20000209, A1 Published 20000908

Abstract: A high-density wiring board having a high connection reliability and produced at low cost. The wiring board is characterized by comprising a board having an electrode and covered with an insulating layer in which a hole is made so as to expose the electrode, a wiring connected to the electrode and formed of a layer adhering to the insulating layer and made of Cr or Ti and a layer adhering to the Cr or Ti layer and made of Cu, a protective film covering the wiring and having therein a hole for soldering, and solder for external connection formed in the hole by diffusion-alloying the Cu layer and reaching the Cr or Ti layer for establishing

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connection.

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